

# Introducing a New Playbook for Process Control

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"AI and Big Data have the potential to transform every area of the economy and our lives. These inflections will also have a profound impact on the semiconductor industry."

Gary E. Dickerson President and CEO, Applied Materials, Inc.



#### Today's Key Takeaways

- 1. Semiconductor complexity is increasing. Fab costs are soaring. Time to yield is worth billions in revenue and profitability.
- 2. The legacy approach to optical wafer inspection and process control is no longer economical. Rising cost per wafer scan is reducing inspection points, and defectivity issues are causing node delays.
- 3. Applied Materials is introducing a new playbook for process control in development since 2016 based on Big Data and AI.
  - Big Data: Applied is introducing a brand new optical inspection system called Enlight<sup>®</sup> that combines industry-leading speed with new optics designed to capture more yield data.
  - AI: Enlight includes ExtractAI<sup>™</sup> technology that combines high-end optical inspection with the best eBeam imaging in the market to quickly classify yield-killing defects and remove noise. The Enlight system with ExtractAI technology gives customers more actionable data, faster than ever before, to accelerate yields and time to market.



## Semiconductor Industry Economic Challenges

#### Fab Cost is Increasing



Source: Applied Materials Internal Data

#### Speeding Time to Market, Reducing Area Under the Yield Curve is Worth Billions



- Foundry/Logic: at 3nm, one week of downtime results in \$25 million in unamortized depreciation cost.
- DRAM: one week of downtime costs 2% of annual revenue plus price erosion.



## Semiconductor Industry Complexity Challenges

SMALLER LINE WIDTHS Smaller particles become yield-killing defects



Process Node

**3D STRUCTURES** Increase process complexity



#### MULTI-PATTERNING Small variances accumulate to produce yield-killing defects



**Final Check** 

If you only inspect here, how do you know which step caused the defect?



#### Legacy Approach: Increasing Optical Inspection Complexity & Cost



Source: Applied Materials internal data

Result: While rising complexity calls for more inspection, higher cost limits inspection points. "Little data."



#### A New Playbook for Process Control Breakthrough #1: Enlight<sup>®</sup> System

- A. Industry's fastest high-end optical scanner
  - Up to 3X cost improvement in critical defect detection
- B. Industry's highest numerical aperture
  - For maximum resolution + higher sensitivity
- C. Brightfield + Greyfield optics
  - To simultaneously collect more data per pass
- D. Tunable polarization
  - Maximize noise suppression
- E. Flexible imaging and computing infrastructure
  - To support AI algorithms



## **Enlight System: Optimized for Big Data Collection**





## Enlight System: Big Data = Faster and Better Yields

#### MULTI-PATTERNING More inspection points enables root cause traceback



#### LINE HEALTH MONITORING More inspection data enables <u>excursion prediction and detection</u>



Stop wafer processing as soon as an issue is identified

"The additional data obtained by line monitoring enables me to accelerate and manage yields in a way that I could never afford to do before." - Leading Customer, June 2020



#### A New Playbook for Process Control Breakthrough #2: Enlight System + ExtractAl<sup>™</sup> Technology

**PROBLEM** Distinguishing defects from "noise"



Process Node



#### Introducing AI Technology to Quickly Classify Defects, Remove Noise



## **Tutorial: Optical and eBeam - Complementary Technologies**

Wafer Coverage
Pixel Resolution
Classify Defects
Defects vs. Noise

Optica		
Data C	apt	ure
FAST		
LOW		
LOW		
LOW		

Beam	
Data Class	sification
SLOW	
HIGH —	Key attributes for
HIGH	data classification
HIGH	





## Applying Big Data + Al Strategy



**1. Unclassified Data** Use Enlight system to quickly generate database of potential defects

2. Classification & Training Use SEMVision system to train ExtractAl to classify defects and noise **3. Inferencing** Enlight with ExtractAl now automatically recognizes specific defects across the wafer map



## **Enlight with ExtractAl Solution: How It Works**









#### Enlight System



ExtractAI Technology



#### SEMVision System



#### **ExtractAl Technology**

- Learns quickly with SEMVision, the industry's leading eBeam review system with the best-in-class imaging, enabling automatic defect classification
- The only real-time active learning using database-to-database connectivity to provide adaptive run-time classification of yield-killing defects and noise
- The most efficient solution: extracts all defects of interest after reviewing only 0.001X of the potential defects
- Provides an actionable defect map 100% classified and noise free
- Delivers more accuracy and value as more wafers are scanned







## **Enlight with ExtractAl: Customer Momentum at Launch**



Enlight Cumulative Revenue\*



- In development since 2016
- Fastest-ramping inspection system in Applied's history
- In production at all leading-edge foundry/logic customers worldwide



## SEMVision<sup>®</sup> eBeam Review

Industry's leading eBeam review system for over 20 years





#### >1,500 Systems at Customer Fabs



### Enlight with ExtractAI: A New Playbook for Process Control

#### **BIG DATA**

Enlight system combines industry-leading speed with new optics designed to capture more yield data.

#### ARTIFICIAL INTELLIGENCE

ExtractAI technology learns to automatically classify yield-killing defects and distinguish defects from noise.





## Delivering the "t" in Applied's New Playbook for PPACt



#### ENABLED BY



#### Enlight with ExtractAI Accelerates Industry Time to Market



